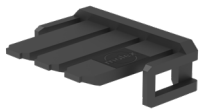




FIT FAMILIES >

COMMON FEATURES AND ADVANTAGES



TERMINAL POSITION ASSURANCE (TPA)

Helps ensure terminals are fully seated in their housing to reduce back-out; retains terminals if main retention feature fails.

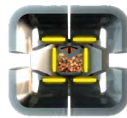
Improves the quality of assembly to avoid back-out issues and therefore can save on costs.



POLARIZATION AND KEYING

Reduces the possibility of misalignment.

Virtually eliminates misalignment and significantly reduces the number of errors associated with improper installation.



MULTIPLE CONTACT POINTS

Provide a variety of critical contact points between the terminal and the mating contact-point application.

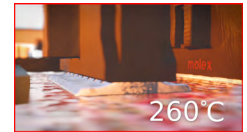
Multiple current paths have significant advantages over contact systems with fewer paths or with only two paths.



TANGLESS TERMINALS

Protect terminals for manufacturers and cable harness assembly teams during packaging and assembly insertion.

Save time and money by reducing failures associated with locking wings on electrical terminals.



REFLOW-CAPABLE HEADERS

Reduce processing requirements and costs.

Reflow soldering is reliable and effective for all pitches of leads and pads, enabling very high-quality circuit boards to be manufactured.

PRODUCT OVERVIEW

A wide range of OEMs require power connectors that also support design flexibility. To meet these needs, Fit Family Connectors offer colored polarized housings with isolated terminals, TPAs, positive locks and tangless terminals.

ADDITIONAL FEATURES

POSITIVE LOCKS

These help ensure mated connector assemblies will not accidentally disengage; indicate to the operator through an audible click that the part is fully mated.

SCOOP PROOF

Contacts are designed to protect critical contacts from damage associated with mating and un-mating.

FULLY ISOLATED CONTACTS

These inhibit arcing between contacts and afford the use of higher voltages as well as better electrical isolation between adjacent contacts.

SEALED PROTECTION

Mini-Fit Sigma Sealed Connectors provides protection from water foam and debris ingress.


















Online Content
(Multiple Languages)

molex

FIT FAMILIES

	Nano-Fit	Micro-Fit	Micro-Fit+	Ultra-Fit	Mini-Fit	Mini-Fit Sigma	Mini-Fit Max	Mega-Fit
Pitch	2.50mm	3.00mm	3.00mm	3.50mm	4.20mm	4.20mm	4.20mm	5.70mm
Style	W-to-B W-to-W	B-to-B W-to-B W-to-W	W-to-B	W-to-B	B-to-B W-to-B W-to-W	W-to-B W-to-W	W-to-B	W-to-B W-to-W
Wire (AWG)	20 to 26	18 to 30	16 to 30	16 to 22	16 to 28	16 to 24	14 to 16	12 to 16
Current (max.)	8.0A	10.5A	12.5A	14.0A	13.0A	13.5A	20.5A	26.0A
Voltage (max.)	250V AC	600V AC	600V AC	600V AC	600V AC	600V AC	600V AC	600V AC
SMT or Reflow Capable	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Glow Wire	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
UL 94V-0	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
TPA	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Operating Temp. (max)	+115°C	+125°C	+105°C	+120°C	+125°C	+105°C	+105°C	+120°C
Blind Mating	No	Yes	No	No	Yes	No	No	No
Sealed Option	No	No	No	No	No	Yes	No	No

Nano-Fit	Micro-Fit	Ultra-Fit	Mini-Fit	Mega-Fit
				
2.50mm pitch 8.0A, 250V 2 to 16 circuits 20 to 26 AWG W-to-B, W-to-W SMT, through hole 115°C Reflow capable	3.00mm pitch 10.5A, 600V 2 to 24 circuits 18 to 30 AWG W-to-B, W-to-W, B-to-B SMT, through hole CPI 125°C Reflow capable Blind mating version	3.50mm pitch 14.0A, 600V 2 to 16 circuits 16 to 22 AWG W-to-B, through hole 120°C Reflow capable Tangless and 6-point contact design	4.20mm pitch 13.0A, 600V 2 to 24 circuits 16 to 28 AWG W-to-B, W-to-W, B-to-B Through hole, Press fit 125°C Reflow capable Wide variety portfolio	5.70mm pitch 26.0A, 600V 2 to 12 circuits 12 to 16 AWG W-to-B, W-to-W Through hole 120°C Reflow capable Tangless and 6-point contact design
 	 	 	 	 

www.molex.com/fit

